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Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1-5. (Canceled).

6. (Withdrawn) A method of manufacturing a solid-state image device, comprising:
forming at least two through holes in a ceramic green sheet;
baking the ceramic green sheet to obtain a ceramic baked product; and
dividing the ceramic baked product to obtain a package so that at least two recessed portions are formed from the at least two through holes in the package,
wherein the at least two through holes are positioned so that the at least two recessed portions are formed at least at one selected from two adjacent side ends of the package, and
the at least two through holes are formed to have shapes surrounded by end faces including linear portions observed when being seen from an upper surface side of the package to form linear portions on end faces defining the at least two recessed portions.

7. (Withdrawn) A method of manufacturing a solid-state image device, comprising:
preparing at least two ceramic green sheets and forming, in the at least two ceramic green sheets, through holes with substantially rectangular shapes on virtual parting lines arranged in a reticulated form observed when being seen from upper surface sides of the at least two ceramic green sheets, with vertices of the substantially rectangular shapes not positioned on the virtual parting lines;
laminating the at least two ceramic green sheets with the virtual parting lines coinciding substantially in their lamination direction to form a laminate;
baking the laminate to obtain a ceramic baked product;
dividing the ceramic baked product along the virtual parting lines to obtain a plurality of packages having recessed portions formed from the through holes.

8. (Withdrawn) A method of manufacturing a solid-state image device, wherein a package with first and second end faces formed by removing a portion at least at one selected from two adjacent side ends of the package is positioned, using a positioning jig provided with first and

second projections coming into contact with the first and second end faces along their shapes respectively, with the first and second projections being brought into contact with the first and second end faces along their shapes respectively, and in this state, a solid-state image element is fixed to the package.

9. (Withdrawn) The method of manufacturing a solid-state image device according to claim 8, wherein when the package is seen from its upper surface side, contact faces between the first and second end faces and the first and second projections are formed substantially in at least one selected from a linear shape and an arc shape.

10-11. (Canceled).

12. (New) A solid-state image device, comprising a solid-state image element and a package that is formed by laminating at least two ceramic sheets and has a rectangular outer shape when being seen from an upper surface side of the package, the package including a member for patterning, on a surface of which a conductor pattern for transmitting signals from the solid-state image element is formed,

wherein the package has first side ends at which no outer lead is formed and second side ends at which outer leads are formed,

at least one corner of the package has a recessed portion having an "L" shape when being seen from the upper surface side, and each of the first side ends of the package has a recessed portion having a "U" shape when being seen from the upper surface side,

the recessed portion having an "L" shape and the recessed portion having a "U" shape are defined respectively by end faces including reference end faces having a linear shape when being seen from the upper surface side, and

the reference end face in the recessed portion having an "L" shape is parallel to the second side ends, the reference end face in the recessed portion having a "U" shape is parallel to the first side ends.

13. (New) The solid-state image device according to claim 12, wherein the reference end faces are formed of the member for patterning.

14. (New) A camera comprising:

a solid-state image device according to claim 12; and

a lens block that has projections coming into contact respectively with the reference end face in the recessed portion having an "L" shape and the reference end face in the recessed portion having a "U" shape along their shapes and a lens focusing external light onto the solid-state image element included in the solid-state image device,

wherein the solid-state image device and the lens block are positioned with the projections being in contact with the reference end faces along their shapes.

15. (New) A camera comprising:

a solid-state image device according to claim 13; and

a lens block that has projections coming into contact respectively with the reference end face in the recessed portion having an "L" shape and the reference end face in the recessed portion having a "U" shape along their shapes and a lens focusing external light onto the solid-state image element included in the solid-state image device,

wherein the solid-state image device and the lens block are positioned with the projections being in contact with the reference end faces along their shapes.